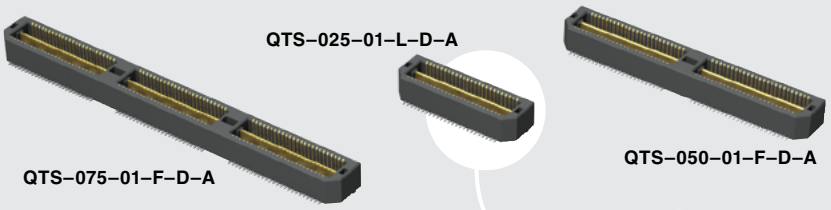
samtec

QSTRIP®



(0.635 mm) .025"

QTS SERIES

HIGH-SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating:
Contact:
1.8 A per pin
(1 pin powered per row)
Ground Plane:
23.1 A per ground plane
(1 ground plane powered)
Operating Temp:
-55 °C to +125 °C
Voltage Rating:
285 VAC
Max Cycles:
100
RoHS Compliant:
Yes

PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (025-075)
Board Stacking:
For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

FILE NO: 090871_0_000

ALSO AVAILABLE
(MOQ Required)

- 11 mm & 16 mm stack height
- 30 µ" (0.76 µm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount

Contact Samtec.

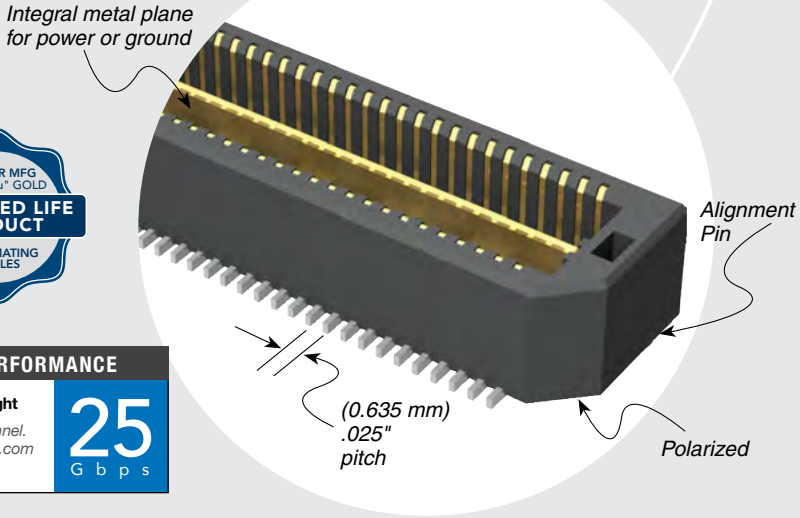
Note: Some lengths, styles and options are non-standard, non-returnable.

Board Mates:
QSS

Cable Mates:
SQCD

Standoffs:
SO

10 YEAR MFG WITH 50 µ" GOLD
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES



HIGH-SPEED CHANNEL PERFORMANCE

QTS/QSS @ 5 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

25 Gbps

QTS	–	NO. OF POSITIONS PER ROW	–	LEAD STYLE	–	PLATING OPTION	–	D	–	A	–	OTHER OPTION

–025, –050, –075
(50 total positions per bank)

Specify LEAD STYLE from chart.

–F
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

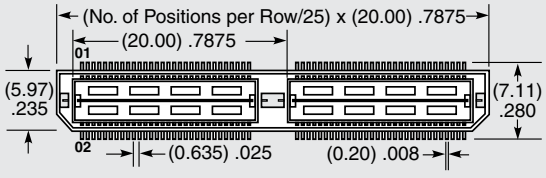
–L
= 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

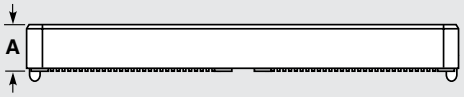
–C*
= Electro-Polished Selective 50 µ" (1.27 µm) min Au over 150 µ" (3.81 µm) Ni on Signal Pins in contact area, 10 µ" (0.25 µm) min Au over 50 µ" (1.27 µm) Ni on Ground Plane in contact area, Matte Tin over 50 µ" (1.27 µm) min Ni on all solder tails

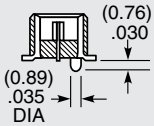
***Note:** –C Plating passes 10 year MFG testing

–K
= (7.00 mm) .275" DIA Polyimide film Pick & Place Pad

–TR
= Tape & Reel







LEAD STYLE	A	MATED HEIGHT
–01	(4.27) .168	(5.00) .197
–02	(7.26) .286	(8.00) .315

Processing conditions will affect mated height. See SO Series for board space tolerances